# AURIX™ TC36x variants

## About this document

### Scope and purpose

This document is an addendum to the TC36x Product Data Sheet and User's Manual, listing all planned product variants, key parameters such as memory size and optional features.

The User's Manual lists functions implemented on the Silicon, but this document counts functions that are pinning dependent; i.e. functions are counted that are connected to at least one package pin. As pins are overlaid with several functions the pinning needs to be checked (see Product Data Sheet) to determine the number of usable functions in an application.

### Naming conventions

Prefix:

- SAK: $T_{ambient}$ Temperature Range from -40 °C up to +125 °C.
- SAL: $T_{ambient}$ Temperature Range from -40 °C up to +150 °C (packaged device).

Feature package:

- P: Standard feature.
- E: Emulation device with all features of the emulated standard type, additionally full MCDS, overlay functionality for calibration, AGBT as trace interface for development (depending on the package).
- C,V,Z: Customer Specific.
- A: ADAS ext. Memory.
- T: ADAS + emulation.
- X: Extended Feature device. These products contain the extended memory (EMEM) of the ADAS subsystem. The ADAS peripherals SPU and RIF are not available.
- M: MotionWise software.
- F: Extended Flash.
- G: Additional Connectivity.
- H: ADAS Standard feature.
- N: Standard feature with AMU.

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# 1 TC36x AA step variants

## 1.1 TC36x AA step (part 1)

A table listing the TC36x AA step variants.

**Table 1 TC36x AA step (part 1)**

| SAK-TC365DP-64F 300W | SAK-TC364DP-64F 300W | SAK-TC367DP-64F 300S | SAL-TC367DP-64F 300S | SAL-TC365DP-64F 300W | SAK-TC365DP-64F 200W | SAK-TC367DP-48F 200S |
|---|---|---|---|---|---|---|
| **Step** | | | | | | |
| AA | AA | AA | AA | AA | AA | AA |
| **Production Status** | | | | | | |
| Standard | Standard | Standard | Standard | Standard | Customer Specific | Customer Specific |
| **Package Type** | | | | | | |
| PG-QFP-176 | PG-QFP-144 | PG-LFBGA-292 | PG-LFBGA-292 | PG-QFP-176 | PG-QFP-176 | PG-LFBGA-292 |
| **Pinout** | | | | | | |
| LQFP 0.5 mm | LQFP 0.5 mm | LFBGA 0.8 mm | LFBGA 0.8 mm | LQFP 0.5 mm | LQFP 0.5 mm | LFBGA 0.8 mm |
| **Reference Silicon** | | | | | | |
| TC36x | TC36x | TC36x | TC36x | TC36x | TC36x | TC36x |
| **Temperature Range (Ambient)** | | | | | | |
| SAK | SAK | SAK | SAL | SAL | SAK | SAK |
| **Chip ID**<br>***Attention*: *The value of SCU_CHIPID in the UCODE field contains the default value 0 not the µCode version.*** | | | | | | |
| 0x87006580 | 0x87006480 | 0x87006780 | 0x87006780 | 0x87006580 | 0x87006580 | 0x86006780 |
| **Cores / Checker Cores** | | | | | | |
| 2/2 | 2/2 | 2/2 | 2/2 | 2/2 | 2/2 | 2/2 |
| **Max. Freq. (MHz)** | | | | | | |
| 300 | 300 | 300 | 300 | 300 | 200 | 200 |
| **Program Flash (MB)** | | | | | | |
| 4 | 4 | 4 | 4 | 4 | 4 | 3 |
| **Data Flash0 (single-ended) (KB)** | | | | | | |
| 128 | 128 | 128 | 128 | 128 | 128 | 128 |
| **Total SRAM (without EMEM and Cache) (KB)** | | | | | | |
| 576 | 576 | 576 | 576 | 576 | 576 | 576 |
| **EMEM Size (KB)** | | | | | | |
| 0 | 0 | 0 | 0 | 0 | 0 | 0 |

## 1 TC36x AA step variants

**Table 1 TC36x AA step (part 1) (continued)**

| SAK-TC365DP-64F 300W | SAK-TC364DP-64F 300W | SAK-TC367DP-64F 300S | SAL-TC367DP-64F 300S | SAL-TC365DP-64F 300W | SAK-TC365DP-64F 200W | SAK-TC367DP-48F 200S |
|---|---|---|---|---|---|---|
| **DSPR (KB)** | | | | | | |
| 192 per CPU | 192 per CPU | 192 per CPU | 192 per CPU | 192 per CPU | 192 per CPU | 192 per CPU |
| **DLMU (KB)** | | | | | | |
| 64 per CPU | 64 per CPU | 64 per CPU | 64 per CPU | 64 per CPU | 64 per CPU | 64 per CPU |
| **PSPR (KB)** | | | | | | |
| 32 per CPU | 32 per CPU | 32 per CPU | 32 per CPU | 32 per CPU | 32 per CPU | 32 per CPU |
| **LMU (KB)** | | | | | | |
| 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| **DAM (KB)** | | | | | | |
| 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| **AMU**[1)] | | | | | | |
| No | No | No | No | No | No | No |
| **ADC (Primary Groups/Channels)** | | | | | | |
| 4/25 | 4/19 | 4/32 | 4/32 | 4/25 | 4/25 | 4/32 |
| **ADC (Secondary Groups/Channels)** | | | | | | |
| 2/25 | 2/21 | 2/28 | 2/28 | 2/25 | 2/25 | 2/28 |
| **ADC (Fast Compare Channels)** | | | | | | |
| 2 | 2 | 2 | 2 | 2 | 2 | 2 |
| **ADC (EDSADC Channels)** | | | | | | |
| 4 | 4 | 4 | 4 | 4 | 4 | 4 |
| **CAN (Modules/Nodes)** | | | | | | |
| 2/2x4 | 2/2x4 | 2/2x4 | 2/2x4 | 2/2x4 | 2/2x4 | 2/2x4 |
| **FlexRay (Modules/Channels)** | | | | | | |
| 1/1x2 | 1/1x2 | 1/1x2 | 1/1x2 | 1/1x2 | 1/1x2 | 1/1x2 |
| **HSSL Modules** | | | | | | |
| 1 | 1 | 1 | 1 | 1 | 1 | 1 |
| **ASCLIN Modules / with ASC & LIN / with 3-wire SPI** | | | | | | |
| 12/12/10 | 12/12/8 | 12/12/10 | 12/12/10 | 12/12/10 | 12/12/10 | 12/12/10 |
| **QSPI Modules / with LVDS** | | | | | | |
| 4/1 | 4/1 | 4/1 | 4/1 | 4/1 | 4/1 | 4/1 |

1 AMU is abbreviated as ASC Modeling Unit. For Additional details about AMU, Contact an Infineon Representative

## 1 TC36x AA step variants

**Table 1 TC36x AA step (part 1) (continued)**

| SAK-TC365DP-64F 300W | SAK-TC364DP-64F 300W | SAK-TC367DP-64F 300S | SAL-TC367DP-64F 300S | SAL-TC365DP-64F 300W | SAK-TC365DP-64F 200W | SAK-TC367DP-48F 200S |
|---|---|---|---|---|---|---|
| **SENT Channels** | | | | | | |
| 10 | 10 | 10 | 10 | 10 | 10 | 10 |
| **MSC Modules** | | | | | | |
| 1 | 1 | 1 | 1 | 1 | 1 | 1 |
| **PSI5 Channels** | | | | | | |
| 2 | 2 | 2 | 2 | 2 | 2 | 2 |
| **PSI5-S Module** | | | | | | |
| Yes | Yes | Yes | Yes | Yes | Yes | Yes |
| **SDMMC Module** | | | | | | |
| No | No | No | No | No | No | No |
| **Max. Ethernet Availability: 1GBit/100Mbit/No** | | | | | | |
| 100Mbit/s (RMII) | 100Mbit/s (RMII) | 1Gbit/s | 1Gbit/s | 100Mbit/s (RMII) | 100Mbit/s (RMII) | 1Gbit/s |
| **MCDS Availability** | | | | | | |
| No | No | No | No | No | No | No |
| **ADAS Cluster Available** | | | | | | |
| No | No | No | No | No | No | No |
| **CIF** | | | | | | |
| No | No | No | No | No | No | No |
| **HSM Available** | | | | | | |
| Yes | Yes | Yes | Yes | Yes | Yes | Yes |

## 1.2 TC36x AA step (part 2)

A continuation table listing the TC36x AA step variants.

**Table 2 TC36x AA step (part 2)**

| SAK-TC364DP-64F300F | SAL-TC364DP-64F300F | SAK-TC364DP-48F300F | SAK-TC364DP-48F200F |
|---|---|---|---|
| **Step** | | | |
| AA | AA | AA | AA |
| **Production Status** | | | |
| Standard | Standard | Customer Specific | Customer Specific |
| **Package Type** | | | |
| PG-QFP-144 | PG-QFP-144 | PG-QFP-144 | PG-QFP-144 |
| **Pinout** | | | |
| TQFP 0.4 mm | TQFP 0.4 mm | TQFP 0.4 mm | TQFP 0.4 mm |
| **Reference Silicon** | | | |
| TC36x | TC36x | TC36x | TC36x |
| **Temperature Range (Ambient)** | | | |
| SAK | SAL | SAK | SAK |
| **Chip ID**<br>***Attention*: *The value of SCU_CHIPID in the UCODE field contains the default value 0 not the µCode version.*** | | | |
| 0x87006480 | 0x87006480 | 0x86006480 | 0x86006480 |
| **Cores / Checker Cores** | | | |
| 2/2 | 2/2 | 2/2 | 2/2 |
| **Max. Freq. (MHz)** | | | |
| 300 | 300 | 300 | 200 |
| **Program Flash (MB)** | | | |
| 4 | 4 | 3 | 3 |
| **Data Flash0 (single-ended) (KB)** | | | |
| 128 | 128 | 128 | 128 |
| **Total SRAM (without EMEM and Cache) (KB)** | | | |
| 576 | 576 | 576 | 576 |
| **EMEM Size (KB)** | | | |
| 0 | 0 | 0 | 0 |
| **DSPR (KB)** | | | |
| 192 per CPU | 192 per CPU | 192 per CPU | 192 per CPU |
| **DLMU (KB)** | | | |
| 64 per CPU | 64 per CPU | 64 per CPU | 64 per CPU |

## 1 TC36x AA step variants

**Table 2 TC36x AA step (part 2) (continued)**

| SAK-TC364DP-64F300F | SAL-TC364DP-64F300F | SAK-TC364DP-48F300F | SAK-TC364DP-48F200F |
|---|---|---|---|
| **PSPR (KB)** | | | |
| 32 per CPU | 32 per CPU | 32 per CPU | 32 per CPU |
| **LMU (KB)** | | | |
| 0 | 0 | 0 | 0 |
| **DAM (KB)** | | | |
| 0 | 0 | 0 | 0 |
| **AMU**[2)] | | | |
| No | No | No | No |
| **ADC (Primary Groups/Channels)** | | | |
| 4/16 | 4/16 | 4/16 | 4/16 |
| **ADC (Secondary Groups/Channels)** | | | |
| 2/21 | 2/21 | 2/21 | 2/21 |
| **ADC (Fast Compare Channels)** | | | |
| 2 | 2 | 2 | 2 |
| **ADC (EDSADC Channels)** | | | |
| 4 | 4 | 4 | 4 |
| **CAN (Modules/Nodes)** | | | |
| 2/2x4 | 2/2x4 | 2/2x4 | 2/2x4 |
| **FlexRay (Modules/Channels)** | | | |
| 1/1x2 | 1/1x2 | 1/1x2 | 1/1x2 |
| **HSSL Modules** | | | |
| 1 | 1 | 1 | 1 |
| **ASCLIN Modules / with ASC & LIN / with 3-wire SPI** | | | |
| 12/12/8 | 12/12/8 | 12/12/8 | 12/12/8 |
| **QSPI Modules / with LVDS** | | | |
| 4/1 | 4/1 | 4/1 | 4/1 |
| **SENT Channels** | | | |
| 10 | 10 | 10 | 10 |
| **MSC Modules** | | | |
| 1 | 1 | 1 | 1 |
| **PSI5 Channels** | | | |
| 2 | 2 | 2 | 2 |

2 AMU is abbreviated as ASC Modeling Unit. For Additional details about AMU, Contact an Infineon Representative

## 1 TC36x AA step variants

**Table 2 TC36x AA step (part 2) (continued)**

| SAK-TC364DP-64F300F | SAL-TC364DP-64F300F | SAK-TC364DP-48F300F | SAK-TC364DP-48F200F |
|---|---|---|---|
| **PSI5-S Module** | | | |
| Yes | Yes | Yes | Yes |
| **SDMMC Module** | | | |
| No | No | No | No |
| **Max. Ethernet Availability: 1GBit/100Mbit/No** | | | |
| 100Mbit/s (RMII) | 100Mbit/s (RMII) | 100Mbit/s (RMII) | 100Mbit/s (RMII) |
| **MCDS Availability** | | | |
| No | No | No | No |
| **ADAS Cluster Available** | | | |
| No | No | No | No |
| **CIF** | | | |
| No | No | No | No |
| **HSM Available** | | | |
| Yes | Yes | Yes | Yes |

## 1.3 TC36x AA step (part 3)

A continuation table listing the TC36x AA step variants.

**Table 3 TC36x AA step (part 3)**

| SAK-TC366DP-64F 300S | SAL-TC366DP-64F 300S | SAK-TC367DP-48F 300S | SAL-TC365DP-64F 200W | SAK-TC364DP-64F 200W | SAK-TC367DP-64F 200S | SAL-TC367DP-64F 200S |
|---|---|---|---|---|---|---|
| **Step** | | | | | | |
| AA | AA | AA | AA | AA | AA | AA |
| **Production Status** | | | | | | |
| Standard | Standard | Customer Specific | Customer Specific | Customer Specific | Customer Specific | Customer Specific |
| **Package Type** | | | | | | |
| PG-LFBGA-180 | PG-LFBGA-180 | PG-LFBGA-292 | PG-QFP-176 | PG-QFP-144 | PG-LFBGA-292 | PG-LFBGA-292 |
| **Pinout** | | | | | | |
| LFBGA 0.8 mm | LFBGA 0.8 mm | LFBGA 0.8 mm | LQFP 0.5 mm | LQFP 0.5 mm | LFBGA 0.8 mm | LFBGA 0.8 mm |
| **Reference Silicon** | | | | | | |
| TC36x | TC36x | TC36x | TC36x | TC36x | TC36x | TC36x |
| **Temperature Range (Ambient)** | | | | | | |
| SAK | SAL | SAK | SAL | SAK | SAK | SAL |
| **Chip ID**<br>***Attention:*** ***The value of SCU_CHIPID in the UCODE field contains the default value 0 not the µCode version.*** | | | | | | |
| 0x87006680 | 0x87006680 | 0x86006780 | 0x87006580 | 0x87006480 | 0x87006780 | 0x87006780 |
| **Cores / Checker Cores** | | | | | | |
| 2/2 | 2/2 | 2/2 | 2/2 | 2/2 | 2/2 | 2/2 |
| **Max. Freq. (MHz)** | | | | | | |
| 300 | 300 | 300 | 200 | 200 | 200 | 200 |
| **Program Flash (MB)** | | | | | | |
| 4 | 4 | 3 | 4 | 4 | 4 | 4 |
| **Data Flash0 (single-ended) (KB)** | | | | | | |
| 128 | 128 | 128 | 128 | 128 | 128 | 128 |
| **Total SRAM (without EMEM and Cache) (KB)** | | | | | | |
| 576 | 576 | 576 | 576 | 576 | 576 | 576 |
| **EMEM Size (KB)** | | | | | | |
| 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| **DSPR (KB)** | | | | | | |
| 192 per CPU | 192 per CPU | 192 per CPU | 192 per CPU | 192 per CPU | 192 per CPU | 192 per CPU |

## 1 TC36x AA step variants

**Table 3 TC36x AA step (part 3) (continued)**

| SAK-TC366DP-64F 300S | SAL-TC366DP-64F 300S | SAK-TC367DP-48F 300S | SAL-TC365DP-64F 200W | SAK-TC364DP-64F 200W | SAK-TC367DP-64F 200S | SAL-TC367DP-64F 200S |
|---|---|---|---|---|---|---|
| **DLMU (KB)** | | | | | | |
| 64 per CPU | 64 per CPU | 64 per CPU | 64 per CPU | 64 per CPU | 64 per CPU | 64 per CPU |
| **PSPR (KB)** | | | | | | |
| 32 per CPU | 32 per CPU | 32 per CPU | 32 per CPU | 32 per CPU | 32 per CPU | 32 per CPU |
| **LMU (KB)** | | | | | | |
| 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| **DAM (KB)** | | | | | | |
| 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| **AMU[3)]** | | | | | | |
| No | No | No | No | No | No | No |
| **ADC (Primary Groups/Channels)** | | | | | | |
| 4/19 | 4/19 | 4/32 | 4/25 | 4/19 | 4/32 | 4/32 |
| **ADC (Secondary Groups/Channels)** | | | | | | |
| 2/18 | 2/18 | 2/28 | 2/25 | 2/21 | 2/28 | 2/28 |
| **ADC (Fast Compare Channels)** | | | | | | |
| 2 | 2 | 2 | 2 | 2 | 2 | 2 |
| **ADC (EDSADC Channels)** | | | | | | |
| 4 | 4 | 4 | 4 | 4 | 4 | 4 |
| **CAN (Modules/Nodes)** | | | | | | |
| 2/2x4 | 2/2x4 | 2/2x4 | 2/2x4 | 2/2x4 | 2/2x4 | 2/2x4 |
| **FlexRay (Modules/Channels)** | | | | | | |
| 1/1x2 | 1/1x2 | 1/1x2 | 1/1x2 | 1/1x2 | 1/1x2 | 1/1x2 |
| **HSSL Modules** | | | | | | |
| 1 | 1 | 1 | 1 | 1 | 1 | 1 |
| **ASCLIN Modules / with ASC & LIN / with 3-wire SPI** | | | | | | |
| 12/12/9 | 12/12/9 | 12/12/10 | 12/12/10 | 12/12/8 | 12/12/10 | 12/12/10 |
| **QSPI Modules / with LVDS** | | | | | | |
| 4/1 | 4/1 | 4/1 | 4/1 | 4/1 | 4/1 | 4/1 |
| **SENT Channels** | | | | | | |
| 10 | 10 | 10 | 10 | 10 | 10 | 10 |

3 AMU is abbreviated as ASC Modeling Unit. For Additional details about AMU, Contact an Infineon Representative

## 1 TC36x AA step variants

**Table 3 TC36x AA step (part 3) (continued)**

| SAK-TC366DP-64F 300S | SAL-TC366DP-64F 300S | SAK-TC367DP-48F 300S | SAL-TC365DP-64F 200W | SAK-TC364DP-64F 200W | SAK-TC367DP-64F 200S | SAL-TC367DP-64F 200S |
|---|---|---|---|---|---|---|
| **MSC Modules** | | | | | | |
| 1 | 1 | 1 | 1 | 1 | 1 | 1 |
| **PSI5 Channels** | | | | | | |
| 2 | 2 | 2 | 2 | 2 | 2 | 2 |
| **PSI5-S Module** | | | | | | |
| Yes | Yes | Yes | Yes | Yes | Yes | Yes |
| **SDMMC Module** | | | | | | |
| No | No | No | No | No | No | No |
| **Max. Ethernet Availability: 1GBit/100Mbit/No** | | | | | | |
| 100Mbit/s (RMII) | 100Mbit/s (RMII) | 1Gbit/s | 100Mbit/s (RMII) | 100Mbit/s (RMII) | 1Gbit/s | 1Gbit/s |
| **MCDS Availability** | | | | | | |
| No | No | No | No | No | No | No |
| **ADAS Cluster Available** | | | | | | |
| No | No | No | No | No | No | No |
| **CIF** | | | | | | |
| No | No | No | No | No | No | No |
| **HSM Available** | | | | | | |
| Yes | Yes | Yes | Yes | Yes | Yes | Yes |

## 1.4 TC36x AA step (part 4)

A continuation table listing the TC36x AA step variants.

**Table 4 TC36x AA step (part 4)**

| SAK-TC364DP-64F200F | SAL-TC364DP-64F200F | SAK-TC366DP-64F200S | SAL-TC366DP-64F200S | SAL-TC364DP-64F200W | SAL-TC364DP-64F300W |
|---|---|---|---|---|---|
| **Step** | | | | | |
| AA | AA | AA | AA | AA | AA |
| **Production Status** | | | | | |
| Customer Specific | Customer Specific | Customer Specific | Customer Specific | Customer Specific | Customer Specific |
| **Package Type** | | | | | |
| PG-QFP-144 | PG-QFP-144 | PG-LFBGA-180 | PG-LFBGA-180 | PG-QFP-144 | PG-QFP-144 |
| **Pinout** | | | | | |
| TQFP 0.4 mm | TQFP 0.4 mm | LFBGA 0.8 mm | LFBGA 0.8 mm | LQFP 0.5 mm | LQFP 0.5 mm |
| **Reference Silicon** | | | | | |
| TC36x | TC36x | TC36x | TC36x | TC36x | TC36x |
| **Temperature Range (Ambient)** | | | | | |
| SAK | SAL | SAK | SAL | SAL | SAL |
| **Chip ID**<br>***Attention*: *The value of SCU_CHIPID in the UCODE field contains the default value 0 not the µCode version.*** | | | | | |
| 0x87006480 | 0x87006480 | 0x87006680 | 0x87006680 | 0x87006480 | 0x87006480 |
| **Cores / Checker Cores** | | | | | |
| 2/2 | 2/2 | 2/2 | 2/2 | 2/2 | 2/2 |
| **Max. Freq. (MHz)** | | | | | |
| 200 | 200 | 200 | 200 | 200 | 300 |
| **Program Flash (MB)** | | | | | |
| 4 | 4 | 4 | 4 | 4 | 4 |
| **Data Flash0 (single-ended) (KB)** | | | | | |
| 128 | 128 | 128 | 128 | 128 | 128 |
| **Total SRAM (without EMEM and Cache) (KB)** | | | | | |
| 576 | 576 | 576 | 576 | 576 | 576 |
| **EMEM Size (KB)** | | | | | |
| 0 | 0 | 0 | 0 | 0 | 0 |
| **DSPR (KB)** | | | | | |
| 192 per CPU | 192 per CPU | 192 per CPU | 192 per CPU | 192 per CPU | 192 per CPU |

## 1 TC36x AA step variants

**Table 4 TC36x AA step (part 4) (continued)**

| SAK-TC364DP-64F200F | SAL-TC364DP-64F200F | SAK-TC366DP-64F200S | SAL-TC366DP-64F200S | SAL-TC364DP-64F200W | SAL-TC364DP-64F300W |
|---|---|---|---|---|---|
| **DLMU (KB)** | | | | | |
| 64 per CPU | 64 per CPU | 64 per CPU | 64 per CPU | 64 per CPU | 64 per CPU |
| **PSPR (KB)** | | | | | |
| 32 per CPU | 32 per CPU | 32 per CPU | 32 per CPU | 32 per CPU | 32 per CPU |
| **LMU (KB)** | | | | | |
| 0 | 0 | 0 | 0 | 0 | 0 |
| **DAM (KB)** | | | | | |
| 0 | 0 | 0 | 0 | 0 | 0 |
| **AMU**[4] | | | | | |
| No | No | No | No | No | No |
| **ADC (Primary Groups/Channels)** | | | | | |
| 4/16 | 4/16 | 4/19 | 4/19 | 4/19 | 4/19 |
| **ADC (Secondary Groups/Channels)** | | | | | |
| 2/21 | 2/21 | 2/18 | 2/18 | 2/21 | 2/21 |
| **ADC (Fast Compare Channels)** | | | | | |
| 2 | 2 | 2 | 2 | 2 | 2 |
| **ADC (EDSADC Channels)** | | | | | |
| 4 | 4 | 4 | 4 | 4 | 4 |
| **CAN (Modules/Nodes)** | | | | | |
| 2/2x4 | 2/2x4 | 2/2x4 | 2/2x4 | 2/2x4 | 2/2x4 |
| **FlexRay (Modules/Channels)** | | | | | |
| 1/1x2 | 1/1x2 | 1/1x2 | 1/1x2 | 1/1x2 | 1/1x2 |
| **HSSL Modules** | | | | | |
| 1 | 1 | 1 | 1 | 1 | 1 |
| **ASCLIN Modules / with ASC & LIN / with 3-wire SPI** | | | | | |
| 12/12/8 | 12/12/8 | 12/12/9 | 12/12/9 | 12/12/8 | 12/12/8 |
| **QSPI Modules / with LVDS** | | | | | |
| 4/1 | 4/1 | 4/1 | 4/1 | 4/1 | 4/1 |
| **SENT Channels** | | | | | |
| 10 | 10 | 10 | 10 | 10 | 10 |

4 AMU is abbreviated as ASC Modeling Unit. For Additional details about AMU, Contact an Infineon Representative

## 1 TC36x AA step variants

**Table 4 TC36x AA step (part 4) (continued)**

| SAK-TC364DP-64F200F | SAL-TC364DP-64F200F | SAK-TC366DP-64F200S | SAL-TC366DP-64F200S | SAL-TC364DP-64F200W | SAL-TC364DP-64F300W |
|---|---|---|---|---|---|
| **MSC Modules** | | | | | |
| 1 | 1 | 1 | 1 | 1 | 1 |
| **PSI5 Channels** | | | | | |
| 2 | 2 | 2 | 2 | 2 | 2 |
| **PSI5-S Module** | | | | | |
| Yes | Yes | Yes | Yes | Yes | Yes |
| **SDMMC Module** | | | | | |
| No | No | No | No | No | No |
| **Max. Ethernet Availability: 1GBit/100Mbit/No** | | | | | |
| 100Mbit/s (RMII) | 100Mbit/s (RMII) | 100Mbit/s (RMII) | 100Mbit/s (RMII) | 100Mbit/s (RMII) | 100Mbit/s (RMII) |
| **MCDS Availability** | | | | | |
| No | No | No | No | No | No |
| **ADAS Cluster Available** | | | | | |
| No | No | No | No | No | No |
| **CIF** | | | | | |
| No | No | No | No | No | No |
| **HSM Available** | | | | | |
| Yes | Yes | Yes | Yes | Yes | Yes |

# 2 Memory maps of TC36x variants

This section describes the influence of the available feature variants on the memory map.

### Program flash

Variants:

- 4 MB: umbrella (2 x 2 MB), see User's Manual.
- 3 MB: 2 + 1 MB (see Figure below).

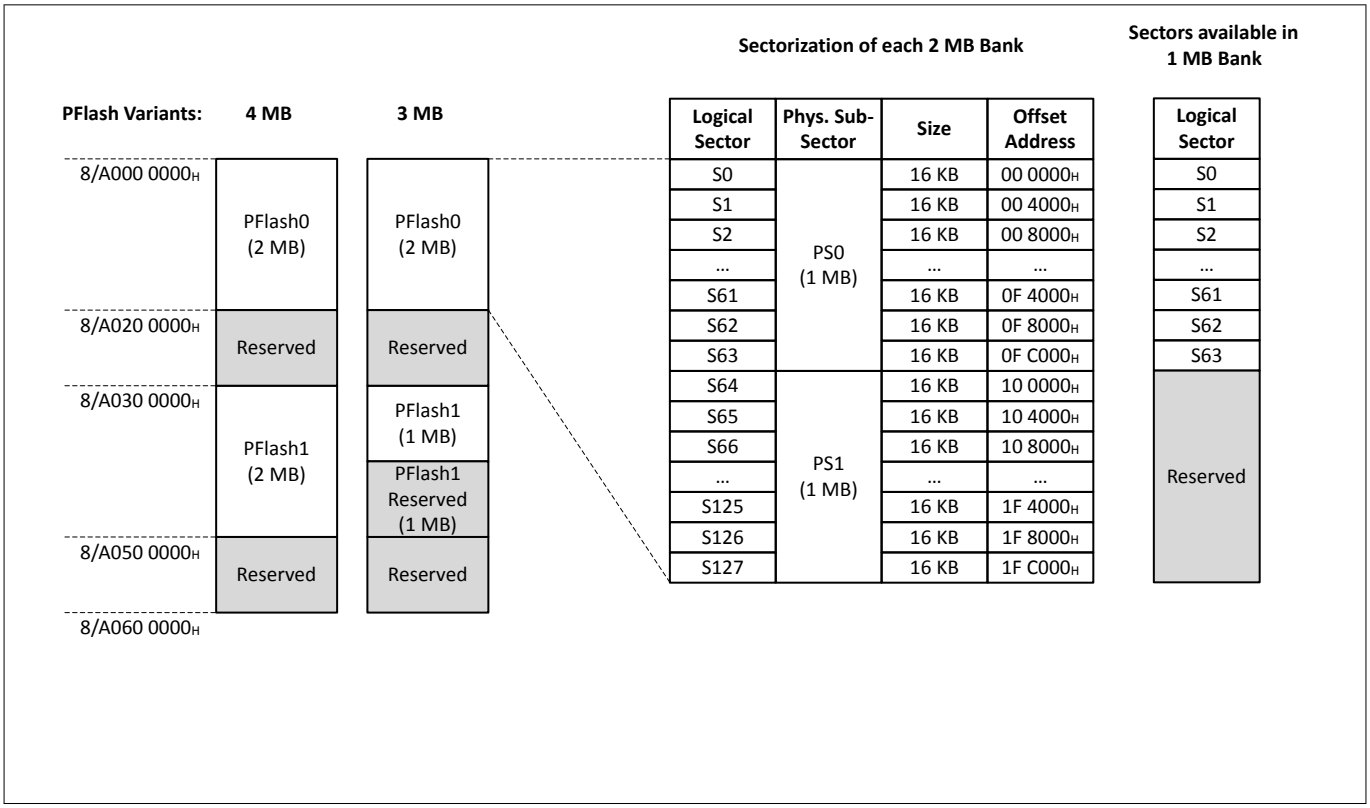


**Figure 1 TC36x PFlash variants**

### Ethernet availability

- 1Gbit/s: umbrella for TC36x, see User's Manual.
- 100Mbit/s (RMII): due to pin limitations in this package the GETH module can be only used in RMII mode.

### ADC availability

- Limitation on availability of ADC channels are caused by pin limitations. See Data Sheet for the pinning table of the package.

# Revision history

| Document version | Date of release | Description of changes |
|---|---|---|
| V1.0 | 2019-03-01 | • First release. |
| V1.1 | 2019-06-13 | • Added new Variants SAK-TC365DP-64F200W,SAK-TC365DP-64F200F, SAK-TC365DP-64F200S,SAK-TC365DP-64F200.<br>• Chapter 1: Added new row in the variant tables called "AMU" with the footnote for additional details.<br>• Chapter: About this document: Feature package definitions are updated to consistent with the product naming nomenclature definition. |
| V1.2 | 2019-08-02 | • For the Product Variants SAK-TC364DP-64F300F, SAL-TC364DP-64F300F , SAK-TC364DP-48F300F ,SAK-TC364DP-48F200F - Number of ADC (Secondary Groups/ Channels) were corrected from 2/24 to 2/21.<br>• For the Product Variants SAK-TC366DP-64F300S , SAL-TC366DP-64F300S - Number of ADC (Secondary Groups/ Channels) were corrected from 2/21 to 2/18. |
| V1.3 | 2020-01-10 | • Chapter 1: Updated the "Production status" for SAK-TC367DP-48F300S, SAK-TC364DP-48F300F to "Customer Specific".<br>• Page 1: About the document:Feature Package 'X' definition is updated to remove CIF.<br>• Chapter 1 and 2:Added new row in the variant tables called "CIF" indicating the Camera Interface availability. |
| V1.4 | 2020-11-18 | • Chapter 1: Removed Bare Die Marking variants SAL-TC360DP-64F300, SAL-TC360DP-64F200. |
| V1.5 | 2021-03-05 | • Chapter 1: Added new Variants SAK-TC364DP-64F200F, SAK-TC364DP-64F200W, SAK-TC366DP-64F200S, SAK-TC367DP-64F200S, SAL-TC364DP-64F200F, SAL-TC364DP-64F200W, SAL-TC364DP-64F300W, SAL-TC365DP-64F200W, SAL-TC366DP-64F200S, SAL-TC367DP-64F200S . |

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